RELIABILITY REPORT

FOR

MAX5184xxxG

PLASTIC ENCAPSULATED DEVICES

May 13, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The MAX5184 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX5184 is a 10-bit, current-output digital-to-analog converter (DAC) designed for superior performance in signal reconstruction or arbitrary waveform generation applications requiring analog signal reconstruction with low distortion and low-power operation. The MAX5184 includesh on-chip precision resistors for voltage-output operation. The MAX5184 is designed for a 10pVs glitch operation to minimize unwanted spurious signal com-ponents at the output. An on-board 1.2V bandgap circuit provides a well-regulated, low-noise reference that can be disabled for external reference operation.

The device is designed to provide a high level of signal integrity for the least amount of power dissipation. It operates from a single 2.7V to 3.3V supply. Additionally, this DAC has three modes of operation: normal, low-power standby, and full shutdown, which provides the lowest possible power dissipation with a 1µA (max) shutdown current. A fast wake-up time (0.5µs) from standby mode to full DAC operation facilitates power conservation by activating the DAC only when required.

The MAX5184 is available in 24-pin QSOP packages and is specified for the extended (-40°C to +85°C) temperature range. Additionally, the MAX5184 is also available in a 24-pin thin QFN with exposed paddle (EP) and is specified for the extended (-40°C to +85°C) temperature range.

B. Absolute Maximum Ratings

Item	Rating
AVDD, DVDD to AGND, DGND	-0.3V to +6V
Digital Inputs to DGND	-0.3V to +6V
OUTP, OUTN, CREF to AGND	-0.3V to +6V
VREF to AGND	-0.3V to +6V
AGND to DGND	-0.3V to +0.3V
AVDD to DVDD	±3.3V
Maximum Current into Any Pin	50mA
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
24-Pin QSOP	762mW
24-Pin Thin QFN	1667mW
Derates above +70°C	
24-Pin QSOP	9.5mW/°C
24-Pin Thin QFN	20.8mW/°C

II. Manufacturing Information

A. Description/Function:	10-Bit, 40MHz, Current/Voltage-Output DACs
B. Process:	TC06
C. Number of Device Transistors:	9464
D. Fabrication Location:	Taiwan
E. Assembly Location:	Hong Kong, Thailand, Philippines or Malaysia
F. Date of Initial Production:	January, 2000

III. Packaging Information

A. Package Type:	**24-Pin QSOP**	**24-QFN (4x4)**
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-0401-0506	# 05-9000-0255
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1	Level 1

IV. Die Information

A. Dimensions:	85 x 97 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal 1 - 0.9 microns / Metal 2 - 0.9 microns (as drawn)
F. Minimum Metal Spacing:	Metal 1 - 0.9 microns / Metal 2 - 0.9 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)
Bryan Preeshl (Executive Director**)**
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 240 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 4.52 \times 10^{-9}$

$\lambda = 4.52$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5370) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The DA70-2 die type has been found to have all pins able to withstand a transient pulse of ±800V Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±200mA.

Table 1
Reliability Evaluation Test Results

MAX5184xxxG

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		240	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	QSOP QFN	77 77	0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

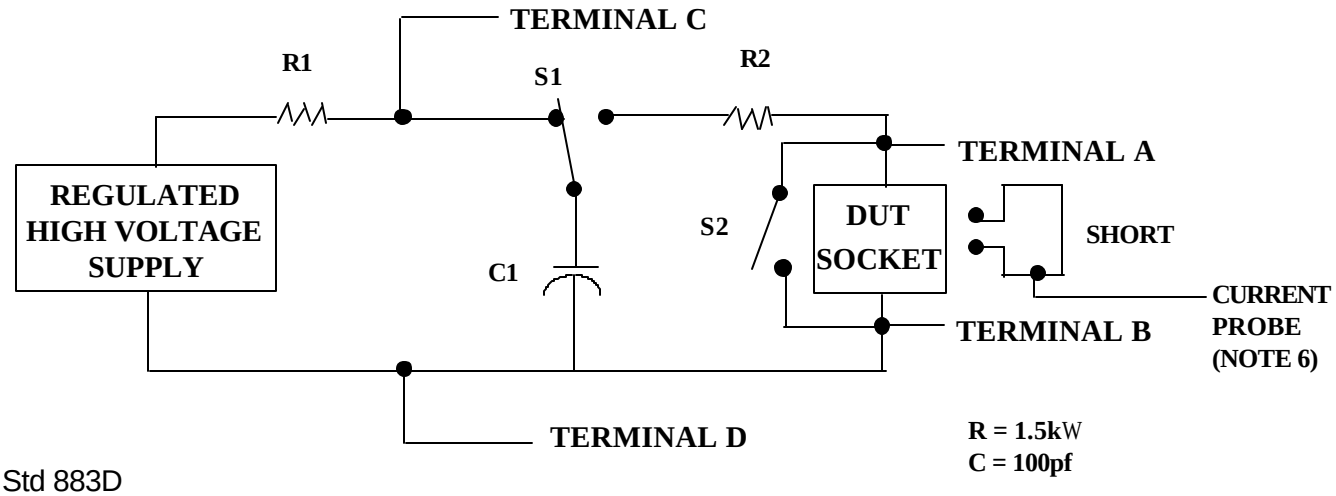
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

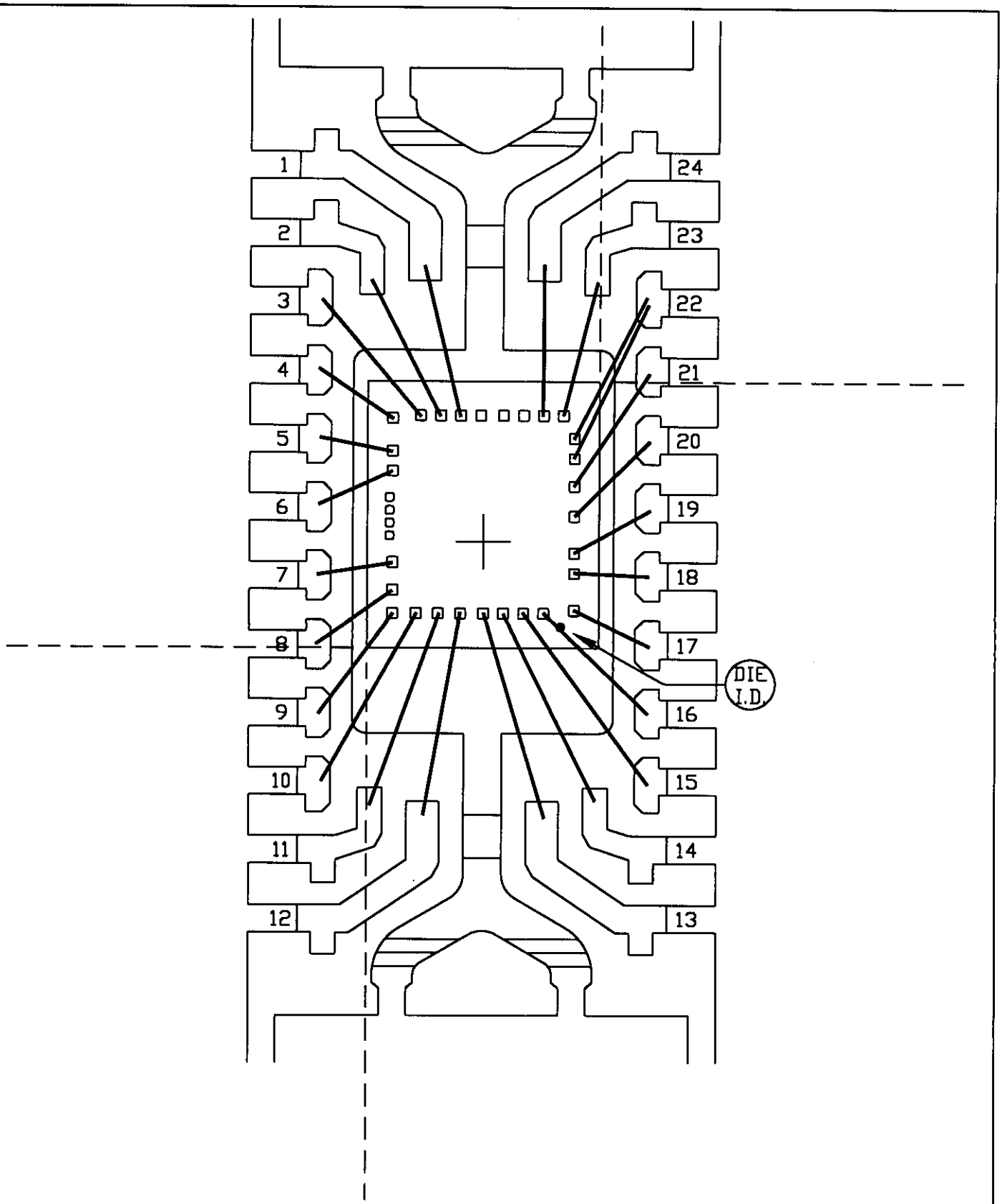
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

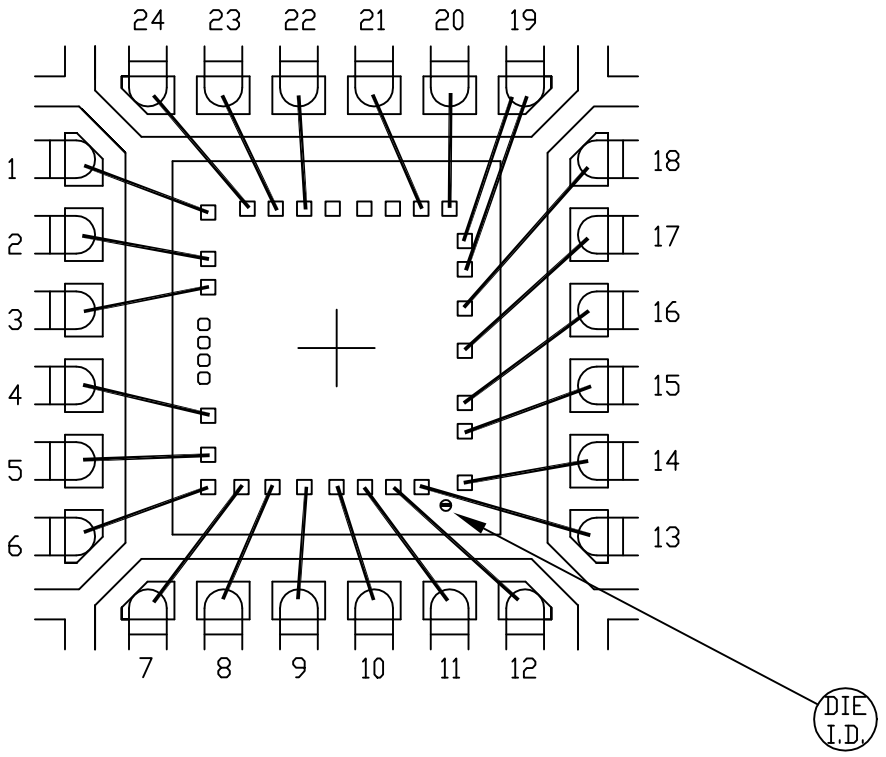


Mil Std 883D
Method 3015.7
Notice 8

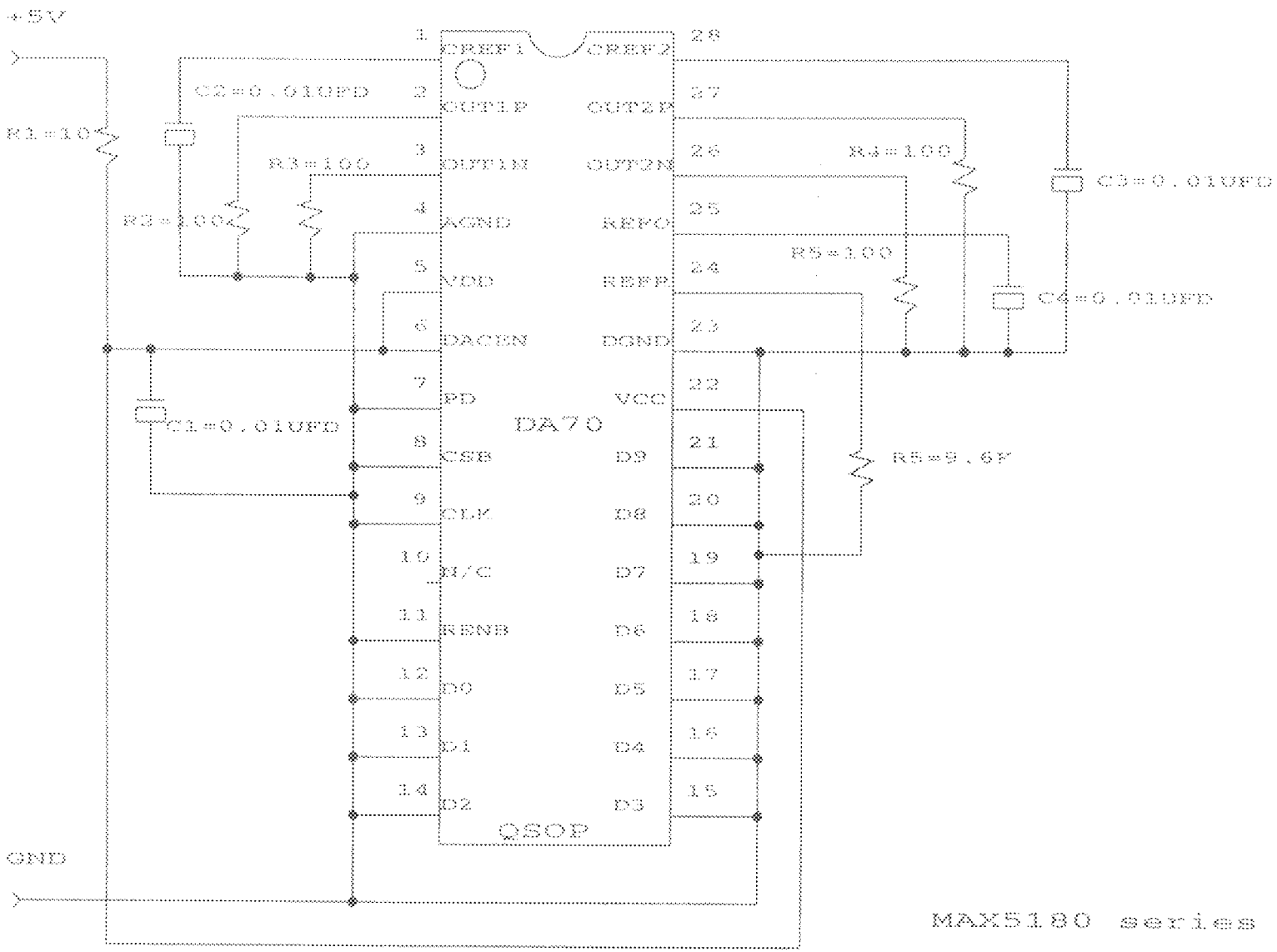


PKG.CODE: E24-1		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 96X140	PKG. DESIGN			BUILDSHEET NUMBER: 05-0401-0506 / REV.: A

4x4x0.8 MM QFN THIN PKG. EXPOSED PAD PKG.



PKG. CODE: T2444-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 110x110	PKG.			BOND DIAGRAM #: 05-9000-0255	REV: A
	DESIGN				



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DA70 BURN-IN CKT1	PROJECT: DA70			
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